



SOT1927-1

HX2QFN16, plastic, thermal enhanced super-thin quad; flat non-leaded package; 16 terminals; 0.4 mm pitch; 2.3 mm x 2.3 mm x 0.38 mm body

16 August 2017

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HX2QFN
Package type industry code	HX2QFN16
Package style descriptive code	X2QFN (plastic thermal enhanced super thin small package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	14-6-2017
Manufacturer package code	SOT1927

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	-	-	2.3	-	mm
E	package width	-	-	2.3	-	mm
A ₂	package height	-	-	0.38	-	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	16	-	



HX2QFN16, plastic, thermal enhanced super-thin quad; flat non-ledged package; 16 terminals; 0.4 mm pitch; 2.3 mm x 2.3 mm x 0.38 mm body

2. Package outline

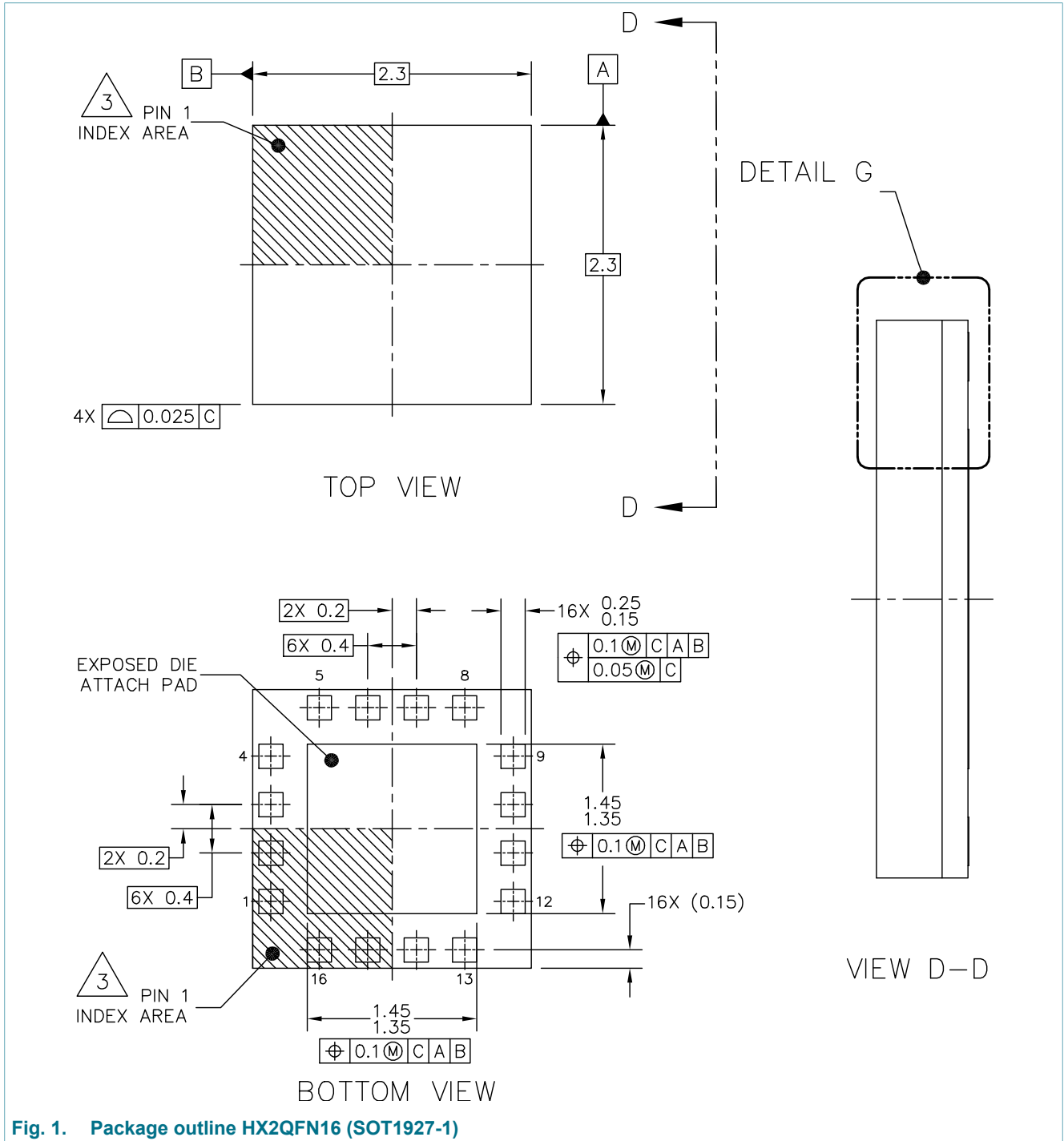


Fig. 1. Package outline HX2QFN16 (SOT1927-1)

HX2QFN16, plastic, thermal enhanced super-thin quad; flat non-leaded package; 16 terminals; 0.4 mm pitch; 2.3 mm x 2.3 mm x 0.38 mm body

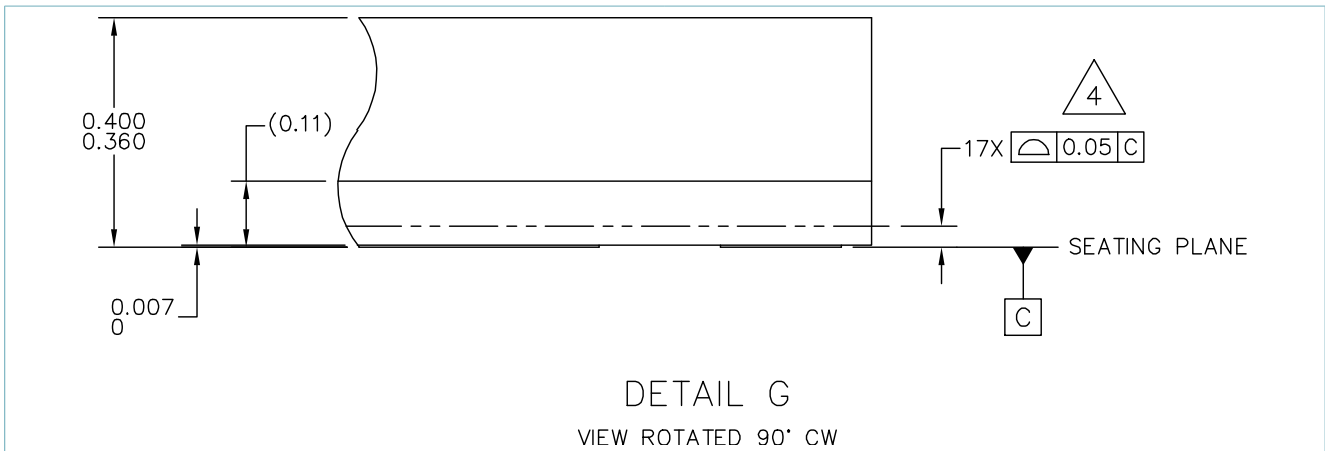


Fig. 2. Package outline dt1 HX2QFN16 (SOT1927-1)

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN ONE CONFIGURATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
5. MIN. METAL GAP SHOULD BE 0.2 MM.

Fig. 3. Package outline note HX2QFN16 (SOT1927-1)

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3. Soldering

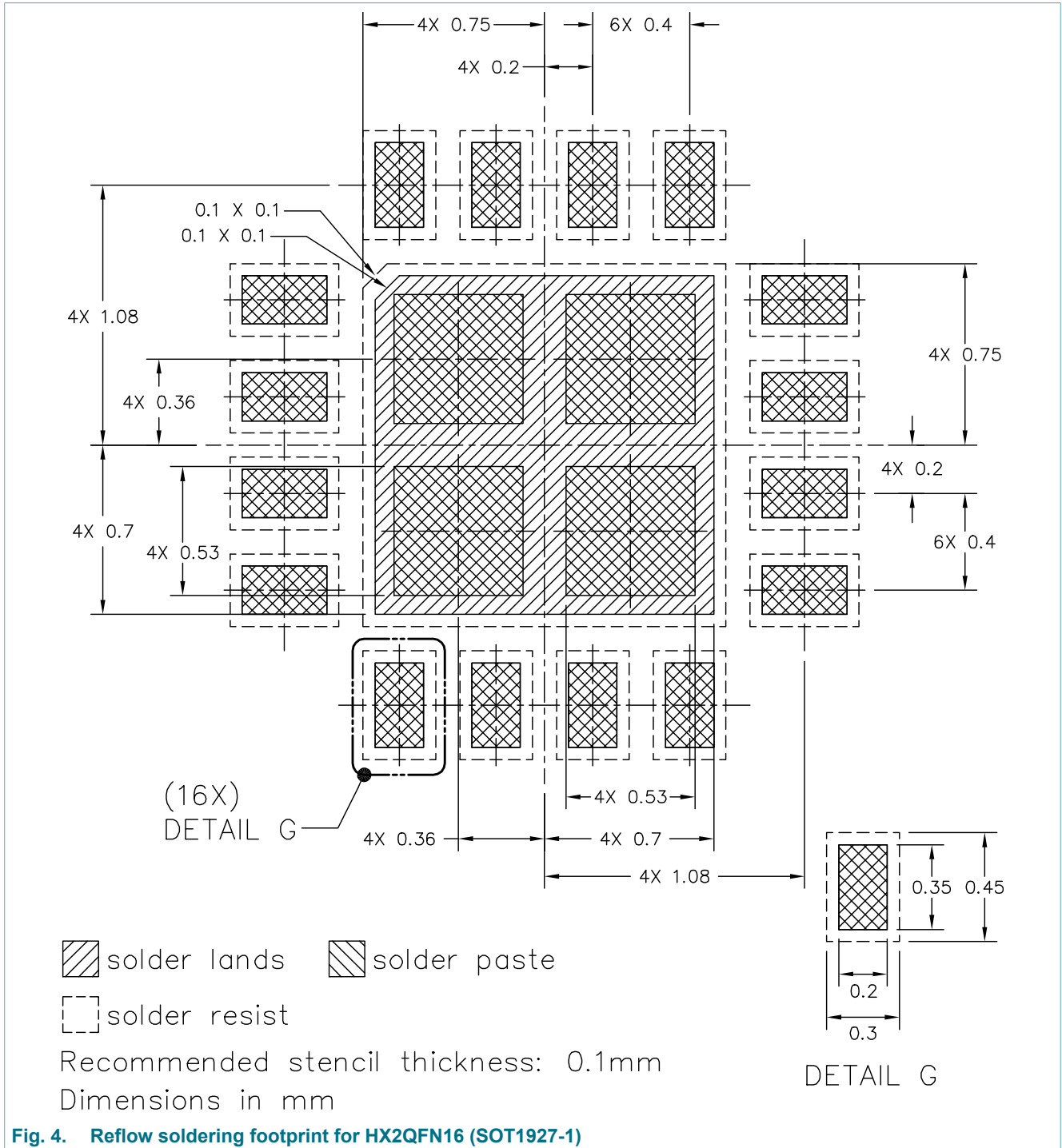


Fig. 4. Reflow soldering footprint for HX2QFN16 (SOT1927-1)

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4. Legal information

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